CALL FOR PAPERS

AICAS 2023
June 11-13

Hangzhou
China

IEEE International Conference on Artificial Intelligence Circuits and Systems
www.aicas2023.org

About AICAS

The entire world and in particular China are massively investing in AI. China is being hosting large ecosystems in AI, as well as numerous conferences. Most of these activities are largely software oriented. Top universities, academies, and Institutes are bringing support, to motivate scientists to contribute. The 5th IEEE International Conference on Artificial Intelligence Circuits and Systems (AICAS'23) is intended to fill the hardware large gap.

*AICAS 2023 is currently planned as a **hybrid event** with in-person presentations along with an option for remote attendees. Speakers should plan to present in person at AICAS 2023. The safety of our speakers and audience remains a priority concern. We will monitor global pandemic conditions and update and adjust he conference format if needed.*

Topics of Interest Include but not Limited to:

- Circuits and systems for AI
- Deep learning/machine learning/AI algorithms
- Tools/platforms for AI
- Architecture for AI computing
- Hardware/software co-design and design automation for AI systems
- Advanced neural network design
- Neuromorphic circuits, processors, and systems and their applications
- Emerging applications: Internet-of-things, healthcare, smart factories, environment
- Emerging devices and materials for AI
- Computer vision algorithms and architectures
- Recommendation system, language/text processing
- Autonomous/unmanned vehicles and drone
- Robotics and automation
- Metaverse and AR/VR
- Deep learning/machine learning for Future Wireless Communications.

Paper Submission

Full-length papers complying with a maximum length of 5 pages (PDF format with the IEEE Conference style), where the 5th page should be reserved for the list of references. Papers must be submitted anonymously. Submitted papers must describe original work that has not been published/accepted/submitted to other conferences or Journals.

Tutorial and Special Session Proposal Submission

Prospective authors of tutorials should submit proposals to the tutorial chairs indicating title of the tutorial, presenters and their short biographies, target audience and prerequisite knowledge of audience, 300 words abstract (for inclusion on webpage and in registration materials), full description (1-2 pages to be used for evaluation), keywords, the detailed contact information of all presenters, and indication of the main contact person.

Important Dates

- Submission of Tutorial Proposal: **January 09, 2023**
- Submission of Special Session Proposal: **January 09, 2023**
- Notification of Acceptance of Special Session Proposal: **January 23, 2023**
- Notification of Acceptance of Tutorial Proposal: **January 23, 2023**
- Submission of Regular Papers and Live Demo: **February 3, 2023**
- Submission of Special Session Full Papers: **February 3, 2023**
- Notification of Paper Acceptance: **March 24, 2023**
- Camera-ready Paper Submission: **April 21, 2023**
- Author & Early bird Registration: **April 21, 2023.**

Special Issues in CASS's Journals

Authors of selected best papers will be invited to submit extended versions of their work for publication in IEEE JETCAS & IEEE TBioCAS special issues.

The Venue is in Hangzhou City

An ancient city with a history of 2200 years, one of the seven ancient capitals in China. It is located 200 km from Shanghai. Hangzhou is the center of science, education, and culture of Zhejiang Province, and is a key national tourism city; it is renowned as "Paradise on Earth". It is well known also for its West Lake site sitting, one of the most attractive tourism regions in China. AICAS'23 will be held in one of the best 5-star hotels in the city center, located close to West Lake, and in walking distance of subway. The region would offer choices of cinemas, supermarket, restaurants and entertainment

Conference Secretariat

Yitian (Claire) Zhang, Westlake University, Hangzhou, China (secretariat@aicas2023.org)

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